

SPECIFICATION FOR APPROVAL

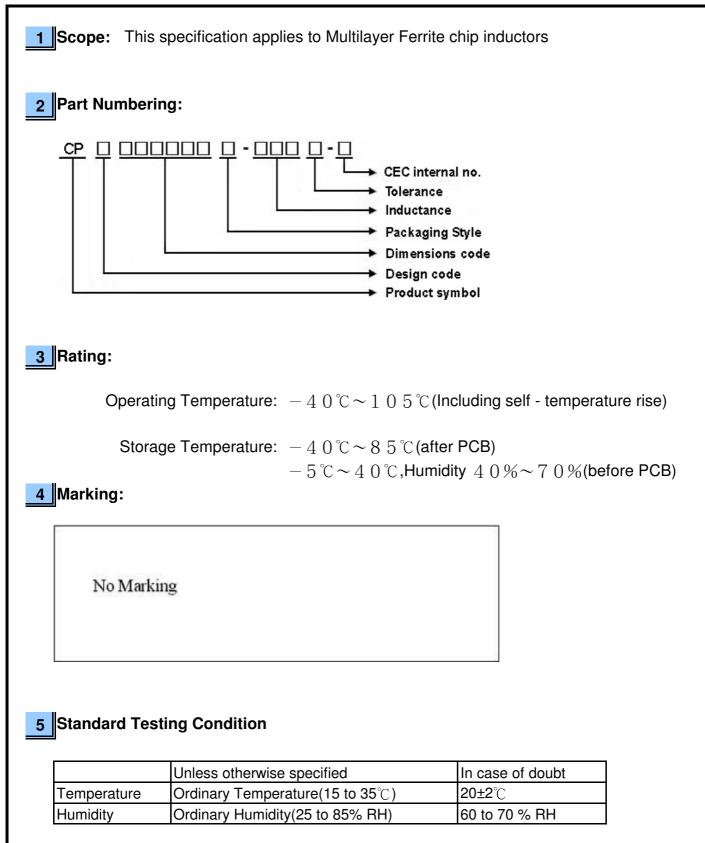
Chilisin P/N:		CPY2	201209T-SE	RIES-NP	
Quantity :	0	Pcs.	Date :	2014/07/07	
Drawing No:					
Customer P/N:					
Customer :					

	SPECIFICATION ACCEPTED BY:	
COMPONENT ENGINEER		
ELECTRICAL ENGINEER		
MECHANICAL ENGINEER		
APPROVED		
REJECTED		
奇力新電子股份有限公司 Chilisin Electronic sCorp No. 29, Alley 301, Tehhsin Rd., Hukou,Hsinchu 303, Taiwan TEL: +886-3- 599-2646 FAX: +886-3- 599-9176 E-mail: sales@chilisin.com.tw http://www.chilisin.com.tw	Chilisin Electronics (No. 78, Puxing Rd., Area, Qingxi Town, E Guangdong,China TEL : +86-769-8773	Dongguan) Co., Ltd. Yuliangwei Administration Dongguan City, -0251~3 3-0232
奇力新電子(河南)有限公 Chilisin Electronics (Henan) Co XiuWu Xian, industry gathering JiaoZuo, Henan China Postal Code:454350 TEL:+86-391-717-0682 FAX:+86-391-717-0666	., Ltd. 句 刀 和电丁(魳) area Chilisin Electronics (Suzhou) Co., Ltd. Rd., Suzhou New District, 350
Drawn by 趙燕玲 annie	Checked by 謝鼎 文 kevin.hsieh	Approved by 詹嘉皓 allen.chan



& TS16949 CHILISIN ELECTRONICS CORP.

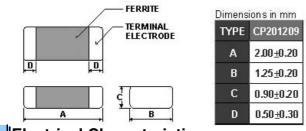
CPY201209T Series Specification





CPY201209T Series Specification

6 Configuration and Dimensions:



7 Electrical Characteristics:

Part No.	Inductance (uH)	Test Freq.	RDC (Ω)Max.	Rated Current (mA)Max.	Tolerance (±%)
CPY201209T-1R0 NP	1	1 MHz,200 mV	0.06	2200	20,30
CPY201209T-2R2 NP	2.2	1 MHz,200 mV	0.1	2000	20,30
CPY201209T-4R7 NP	4.7	1 MHz,200 mV	0.3	900	20,30

NOTE: □-tolerance M=±20% / T=±30%

1.Operating temperature range $-4~0~{\rm °C}$ $\sim 1~0~5~{\rm °C}$ (Including self - temperature rise)

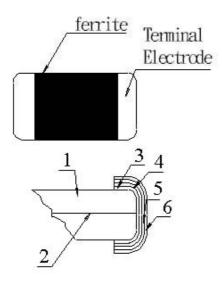
2.Rate Current : Applied the current to coils, the temperature rise shall not be more than $30^\circ\!\mathrm{C}$

"-N" FOR COMPLETELY LEAD FREE TYPE(INCLUDING FERRITE BODY & SOLDER)



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8 CPY201209T Series 8.1 Construction:



8.2 Material List:

NO	PART	MATERIAL
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn



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9 Reliability Of Ferrite Multilayer Chip Inductor

٥V	Item	Specification	Test Method
-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	Deflection: 2.0mm
		ferrite	Keeping Time: 30sec
			*For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate
			Oscillation Frequency: 10 to 55 to 10Hz for 1min
			Amplitude: 1.5mm
			Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
		More than 75% of the terminal	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5°C
		with solder.	Immersion Time: 10±1sec
		Inductance: within ±20% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150°C, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245 \pm 5 $^{\circ}$ C (Pb-Free)
			Immersion Time: 4±1sec

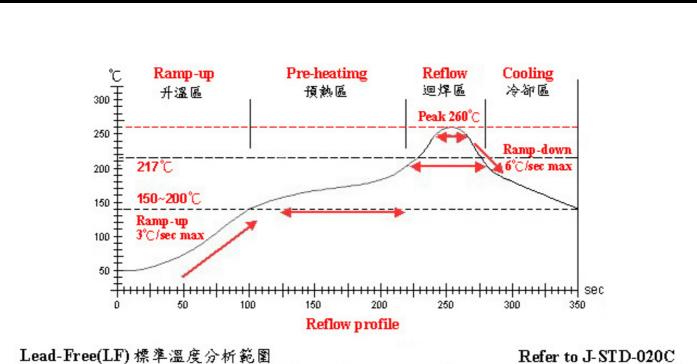
1-2.Environmental Performance

No	Item	Specification		Test Method	
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:		
		Inductance:within±20% of	Step	Temperature (℃)	Time (min)
		initial value	1	-40±3	30
			2	25±2	3
			3	105±3	30
			4	25±2	3
			Total: 100c	cycles	
			Measured	after exposure in the room co	ndition for 24hrs
1-2-2	Humidity Resistance		Temperatu	re: 40±2℃	
			Relative Hu	umidity: 90 ~ 95% / Time: 100	0hrs
			Measured	after exposure in the room co	ndition for 24hrs
1-2-3	High		Temperatu	re: 85±3℃	
	Temperature Resistance		Relative Hu	umidity: 20%	
			Applied Cu	rrent: Rated Current / Time: 1	000hrs
			Measured	after exposure in the room co	ndition for 24hrs
1-2-4	Low		Temperatu	re: -40±3℃	
	Temperature Resistance		Relative Hu	umidity: 0% / Time: 1000hrs	
			Measured a	after exposure in the room co	ndition for 24hrs



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管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T.~150℃	150°C ~ 200°C	21 7℃	260±5° C	Peak Temp. ~ 150°C
標準時間 Time spec.		60 ~ 180 sec	60 ~ 150sec	20 ~ 40 sec	()
實際時間 Time result	_	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	—

NOTE :

1. Re-flow possible times : within 2 times

2. Nitrogen adopted is recommended while in re-flow

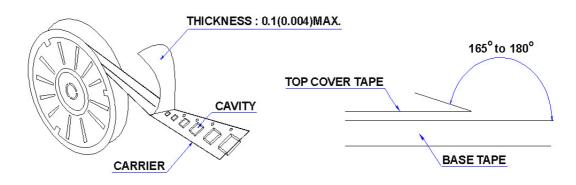


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11 Packaging:

11.1 Packaging -Cover Tape

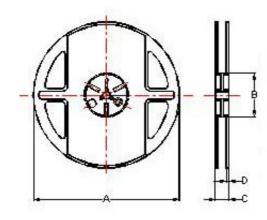
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

ТҮРЕ	BULK	PCS/REEL
CP160808	1	4000
CP201209	1	4000
CP201212	1	3000
CP 32 16 11	1	3000

11.3 Reel Dimensions



Dimensions in mm				
TYPE	A	В	С	D
CP Series	178	60	12	1.5

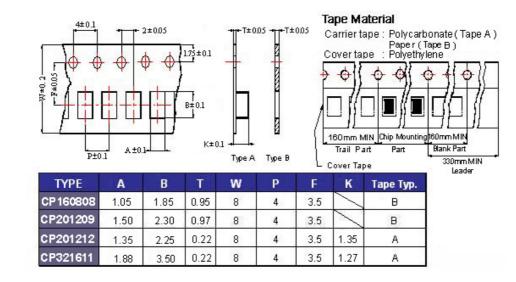


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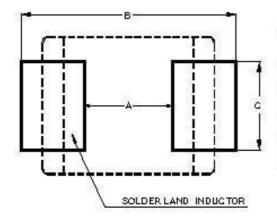
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11 Packaging:

11.4 Tape Dimensions in mm



12 Recommended Land Pattern:



Dimensions in mm						
TYPE	Α	В	C			
CP160808	0.7 ~ 0.8	1.8 ~ 2.0	0.6 ~0			
CP201209	1.0 ~ 1.2	2.6 ~4.0	1.0~1			
CP201212	1.0 ~ 1.2	2.6 ~4.0	1.0~1			
		text and the second				

2.0

4.2~5.2

1.2

13 Note:

1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.

CP321611

- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)



单击下面可查看定价,库存,交付和生命周期等信息

>>CHILISIN(奇力新)

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